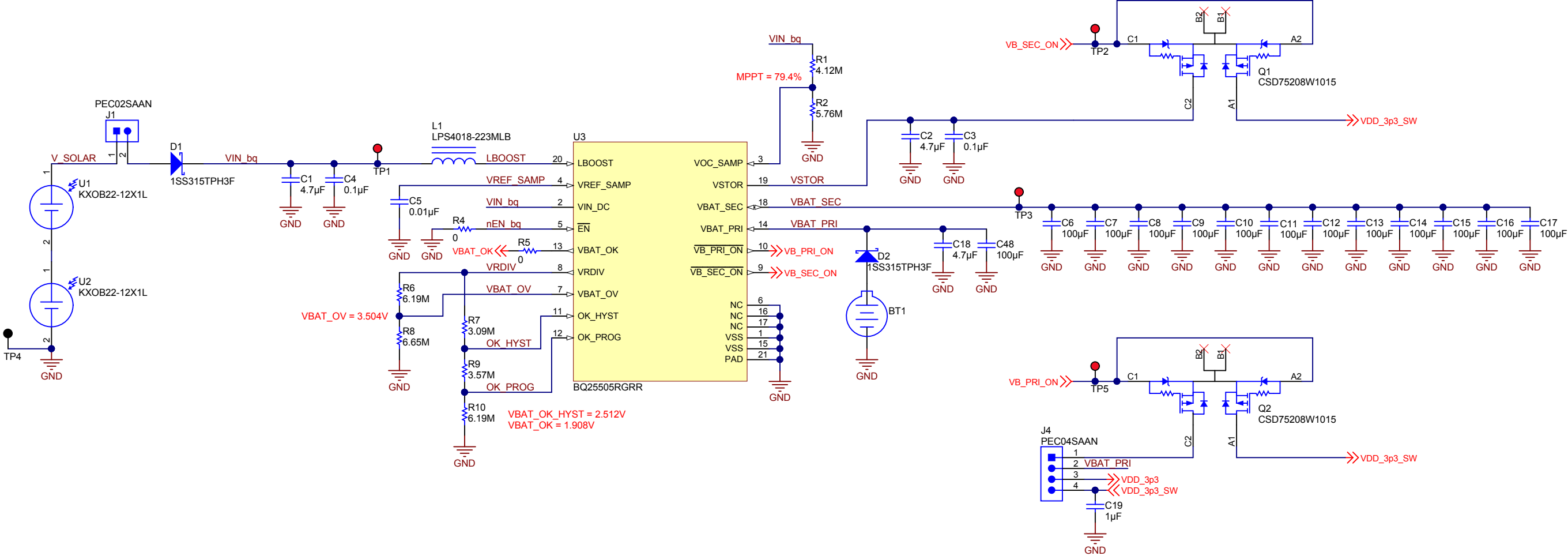


Energy Harvesting Power Management



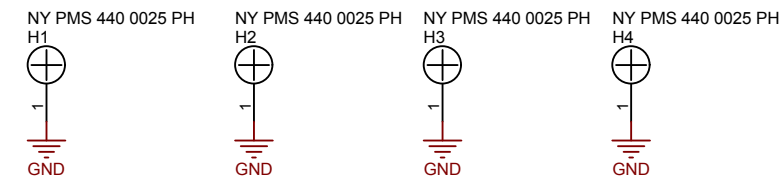
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TID #: TIDA-00488	Project Title: Energy Harvesting Ambient Light and Environment	
Number: ISE4039	Rev: E3	Sheet Title: Energy Harvesting
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 4
Drawn By: Kelly Fernandez	File: ISE4039 Energy Harvesting.SchDoc	Size: B
Engineer: Kelly Fernandez	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



Networks

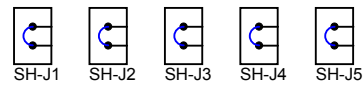




PCB Number: ISE4039  
PCB Rev: E3

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ZZ2

Assembly Note

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3


Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4

### Assembly Note

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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TID #: <a href="#">TIDA-00488</a>	Project Title: <a href="#">Energy Harvesting Ambient Light and Environment S</a>		
Number: <a href="#">ISE4039</a>	Rev: <a href="#">E3</a>	Sheet Title: <a href="#">Hardware</a>	
SVN Rev: Version control disabled	Assembly Variant: <a href="#">001</a>	Sheet: <a href="#">4</a> of <a href="#">4</a>	
Drawn By: <a href="#">Kelly Fernandez</a>	File: <a href="#">ISE4039_TID_Hardware_SchDoc</a>	Size: B	
Engineer: <a href="#">Kelly Fernandez</a>	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>		

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